



Automatic Vision Inspection System

MODEL IV-T3300

Automatic 2D and 3D Vision Inspection machine for wire bonds and other surface defects.

Large working area for inspecting different types of semicon packages, modules or PCB assemblies.



Key Features

- Clean and Simple Design for Easy Maintenance
- Flexibility to Dock with Different Material Handling Systems:
 - JEDEC Tray
 - Carrier Boat
 - Waffle Pack
 - Lead Frame
 - Nikko Rack
 - PCB Assembly
- Large Inspection Area of 600 mm X 550 mm
- Available in Single or Dual Track Loading Option
- Unique Ergonomic Access Door Design
- Touch Screen Monitor for Easy Operation
- SECS/GEM Communication

Component Technology Pte Ltd